WHAT IS CLAIMED IS:

1. An exposure apparatus having an illuminating optics unit for irradiating a reticle, on which a predetermined pattern has been formed, with expbsing light emitted from an exposing light source, a reticle stage on which the reticle is placed, a projection optics unit for projecting the predetermined pattern of the reticle onto a substrate, and a substrate stage on which the substrate is placed, said apparatus comprising:

at least one chamber for internally accommodating the illuminating optics unit, the reticle stage, the projection optics unit and the substrate stage;

first pressure control means for making pressure inside the chamber higher than pressure outside the chamber; and

first correction means for correcting optical characteristics of the projection optics unit in accordance with a value of pressure inside the chamber.

The apparatus according to claim 1, wherein the 20 reticle is irradiated with exposing light, which has been emitted by the exposing light source, via the illuminating optics unit, the predetermined pattern that has been formed on the reticle is projected onto the 25 substrate via the pr ϕ jection optics unit to expose the

10

substrate to the pattern, and the exposing light has an optical path the entirety of which is sealed within at least one chamber, said apparatus further comprising:

second pressure control means for making pressure inside this chamber higher than pressure outside this chamber; and

second correction means for correcting optical characteristics of the projection optics unit in accordance with a value of pressure inside this chamber.

10

5

- 3. The apparatus according to claim 1, wherein the interior of said chamber is filled with inert gas.
- 4. The apparatus according to claim 3, wherein the

 15 inert gas is nitrogen gas or helium gas or a mixed gas

 of nitrogen gas and helium gas.
 - 5. The apparatus according to claim 1, wherein control is performed in such a manner that pressure inside said chamber is made higher, by a fixed amount, than pressure outside the chamber
 - 6. The apparatus according to claim 1, wherein pressure inside said chamber is constant.

25

10

15

20

- 7. The apparatus according to claim 1, further comprising a first pressure sensor for sensing the value of pressure inside said chamber and a second pressure sensor for sensing value of pressure outside said chamber.
- 8. The apparatus according to claim 1, wherein said first correction means estimates amount of change in optical characteristics of said projection optics unit based upon index of refraction, which varies in accordance with the value of pressure inside said chamber, and corrects the optical characteristics of said projection optics unit based upon the estimated amount of change in optical characteristics of said projection optics unit.
- 9. The apparatus according to claim 1, further comprising a substrate load-lock chamber in the vicinity of said substrate stage and a reticle load-lock chamber in the vicinity of said reticle stage.
- 10. The apparatus according to claim 1, wherein said illuminating optics unit, said reticle stage, said projection optics unit and said substrate stage are accommodated in respective ones of separate chambers.

15

20

11. The apparatus according to claim 1, wherein said illuminating optics unit, said reticle stage, said projection optics unit and said substrate stage are accommodated in at least two separate chambers.

12. A method of manufacturing a semi/conductor device, comprising the steps of:

placing a group of manufacturing equipment for various processes, inclusive of the exposure apparatus having an illuminating optics unit for irradiating a reticle, on which a predetermined pattern has been formed, with exposing light emitted from an exposing light source, a reticle stage on which the reticle is placed, a projection optics unit for projecting the predetermined pattern of the reticle onto a substrate, and a substrate stage on which the substrate is placed, said apparatus comprising:

at least one chamber for internally accommodating the illuminating optics unit, the reticle stage, the projection optics unit and the substrate stage;

first pressure control means for making pressure inside the chamber higher than pressure outside the chamber; and

25 first correct on means for correcting optical

10

15

characteristics of the projection optics unit in accordance with a value of pressure inside the chamber, in a plant for manufacturing semiconductor devices; and manufacturing a semiconductor device by a plurality of processes using this group of manufacturing equipment.

13. The method according to claim 12, further comprising:

interconnecting the manufacturing equipment by a local-area network; and

communicating, by data communication, information relating to at least one piece of manufacturing equipment in said group thereof between the local-area network and an external network outside said plant.

14. The method according to claim 13, wherein maintenance information for said manufacturing equipment is obtained by accessing, by data communication via the external network, a database provided by a vendor of said manufacturing equipment or by a user, or production management is performed by data communication with a plant other than said first-mentioned plant via the external network.

10

20

15. A plant for manufacturing a semi-conductor device, comprising:

a group of manufacturing equipment for various processes, inclusive of the exposure apparatus having an illuminating optics unit for irradiating a reticle, on which a predetermined pattern has been formed, with exposing light emitted from an exposing light source, a reticle stage on which the reticle is placed, a projection optics unit for projecting the predetermined pattern of the reticle onto a substrate, and a substrate stage on which the substrate is placed, said apparatus comprising:

at least one chamber for internally accommodating the illuminating optics unit, the reticle stage, the projection optics unit and the substrate stage;

first pressure control means for making pressure inside the chamber higher than pressure outside the chamber; and

first correction means for correcting optical characteristics of the projection optics unit in accordance with a value of pressure inside the chamber;

a local-area network for interconnecting the group of manufacturing equipment; and

a gateway for making it possible to access, from 25 said local-area network, an external network outside the

plant;

whereby information relating to at least one of the pieces of manufacturing equipment can be communicated by data communication.